

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	293	((134/198,199,200,902.ccls. or 216/2, 92.ccls.) or 156/345.21,345.51,345.54, 345.55.ccls.) and @pd>"20061206"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/27 07:44
L2	1670	(tokyo and electron).as. and @pd>"20061206"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/27 07:45
L3	25	2 and (egashira or kamikawa).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/27 07:45
L4	731	((nozzle or orifice or spray\$3 or jet\$4) with (container or chamber or vessel or tank) and (semiconductor wafer substrate workpiece) with (chuck hold\$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/27 07:54
L5	15	((nozzle or orifice or spray\$3 or jet\$4) with (container or chamber or vessel or tank) and (semiconductor wafer substrate workpiece) with (chuck hold\$3) and pedestal).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/27 07:48
L6	5	((nozzle or orifice or spray\$3 or jet\$4) with (container or chamber or vessel or tank) and (semiconductor wafer substrate workpiece) with (chuck hold\$3) and circular adj plate).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/27 07:50
L7	36	((nozzle or orifice or spray\$3 or jet\$4) with (container or chamber or vessel or tank) and (semiconductor wafer substrate workpiece) with parallel with (chuck hold\$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/27 07:50
L8	10305	((nozzle or orifice or spray\$3 or jet\$4) with oblique\$2 (container or chamber or vessel or tank) and (semiconductor wafer substrate workpiece) with (chuck hold\$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/27 07:50
L9	3	((nozzle or orifice or spray\$3 or jet\$4) with oblique\$2 with (container or chamber or vessel or tank) and (semiconductor wafer substrate workpiece) with (chuck hold\$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/27 07:51

## EAST Search History

L11	908	134/153.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/27 07:53
L12	169	((nozzle or orifice or spray\$3 or jet\$4) with (container or chamber or vessel or tank) and (semiconductor wafer substrate workpiece) with (chuck hold\$3)) and 11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/27 07:54